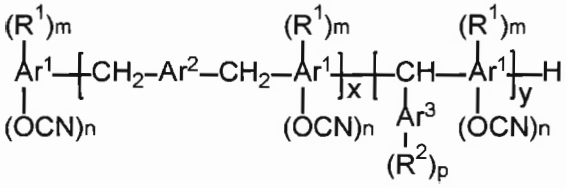
CLAIMS

[Claim 1]

A resin composition for a printed wiring board comprising:

a cyanate compound (A) represented by following general formula (1); and

an epoxy resin (B),



(1)

wherein Ar^1 represents an aryl group, Ar^2 each independently represents a divalent substituent selected from the group consisting of a phenylene group, a naphthylene group, and a biphenylene group, Ar^3 each independently represents a p+1-valent substituent selected from the group consisting of a p+1-valent phenyl group, a p+1-valent naphthyl group, and a p+1-valent biphenyl group, R^1 each independently represents a monovalent substituent selected from the group consisting of a hydrogen atom, an alkyl group, and an aryl group, R^2 each independently represents a monovalent substituent selected from the group consisting of a hydrogen atom, an alkyl group, an aryl group, and a cyanato group, n represents number of cyanato groups bonded to Ar^1 and is an integer of 1 to 3, m represents number of R^1 bonded to Ar^1, n + m + 2 is equal to or less than number of

possible bonds to Ar^1, p represents number of R^2 bonded to Ar^3 and is an integer of 1 to 9, x and y represent a ratio of repeating units, x is 1, whereas y is 0.25 to 2.0, and the repeating units for x and y may each be continuously arranged or may be alternately or randomly arranged with each other.

[Claim 2]

The resin composition for the printed wiring board according to claim 1, wherein Ar^1 comprises an m+n+1-valent or m+n+2-valent phenyl group or an m+n+1-valent or m+n+2-valent biphenyl group,

Ar^2 comprises a phenylene group or a biphenylene group, and

Ar^3 comprises a p+1-valent phenyl group or a p+1-valent biphenyl group.

[Claim 3]

The resin composition for the printed wiring board according to claim 1, wherein Ar^1 comprises an m+n+1-valent or m+n+2-valent phenyl group,

Ar^2 comprises a phenylene group, and

Ar^3 comprises a p+1-valent phenyl group.

[Claim 4]

The resin composition for the printed wiring board according to claim 1, wherein Ar^1 comprises an m+n+1-

valent or m+n+2-valent phenyl group,

Ar^2 comprises a biphenylene group, and

Ar^3 comprises a p+1-valent phenyl group.

[Claim 5]

The resin composition for the printed wiring board according to claim 1, wherein a content of the cyanate compound (A) is 1 to 90 parts by mass based on 100 parts by mass of resin solids in the resin composition for a printed wiring board.

[Claim 6]

The resin composition for the printed wiring board according to claim 1, further comprising a filler (C).

[Claim 7]

The resin composition for the printed wiring board according to claim 1, further comprising one or more compounds selected from the group consisting of a cyanate compound (D) other than the cyanate compound (A), a maleimide compound (E), and a phenolic resin (F).

[Claim 8]

The resin composition for the printed wiring board according to claim 1, wherein the epoxy resin (B) comprises one or more epoxy resins selected from the group consisting of a biphenyl aralkyl-based epoxy resin,

a naphthylene ether-based epoxy resin, a polyfunctional phenol-based epoxy resin, and a naphthalene-based epoxy resin.

[Claim 9]

The resin composition for the printed wiring board according to claim 6, wherein a content of the filler (C) is 50 to 1600 parts by mass based on 100 parts by mass of the resin solids in the resin composition for a printed wiring board.

[Claim 10]

A prepreg comprising:

a base material; and

the resin composition for the printed wiring board according to claim 1 with which the base material is impregnated or coated.

[Claim 11]

A metal foil-clad laminate comprising:

a laminate of at least one or more of the prepregs according to claim 10 stacked; and

a metal foil disposed on one surface or both surfaces of the laminate.

[Claim 12]

A resin composite sheet comprising:

a support; and

the resin composition according to claim 1 applied and dried on a surface of the support.

[Claim 13]

A printed wiring board comprising:

an insulating layer comprising the resin composition according to claim 1; and

a conductor layer formed on a surface of the insulating layer.